IN THE CLAIMS

This listing of claims replaces all prior listings:

1. (Currently Amended) An IC card comprising:

an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, a sealing material which encapsulates said IC chip, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate and formed on said IC chip through said sealing material; and

a core layer comprising a plurality of sheet materials having said IC module disposed therebetween,

wherein,

in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole (a) for containing therein said IC chip said sealing material and said chip reinforcing plate, and (b) formed to penetrate the adjacent sheet materials in a region corresponding to an IC mounted portion of said IC module before placing said IC chip therein,

said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module,

a relationship of $(B1 + C1) - 20\ \mu m \leq A \leq (B1 + C1) + 10\ \mu m$ is satisfied, where A (μm) represents the sum of heights of said through holes, B1 (μm) represents a projection height from an IC mounted surface of said IC module, and C1 (μm) represents a projection height from an IC non-mounted surface of said IC module,

the relationships $B = B1 \pm 30\ \mu m$, and $C = C1 \pm 30\ \mu m$ are satisfied, wherein B (μm) represents a height of said through hole on the side of the IC mounted surface of said IC module, and C (μm) represents a height of said through hole on the side of the IC non-mounted surface of said IC module, and

said through holes are larger than at least one of a length and a width of said sealing material and than at least one of a length and a width of said chip reinforcing plate so as to form at least one empty region in said through holes.

2. - 5. (Cancelled)

6. (Previously Presented) The IC card according to claim 1, wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module, and an outer core sheet stacked on at least one of said pair of inner core sheets.

7. (Original) The IC card according to claim 1, wherein said core layer has a rewritable display layer formed on at least one surface of said core layer.

8. (Original) The IC card according to claim 1, wherein, in said sheet materials constituting said core layer, at least a pair of sheet materials having said IC module disposed therebetween includes a material comprising a copolymer of terephthalic acid, cyclohexanedimethanol and ethylene glycol, and polycarbonate.

9. (Original) The IC card according to claim 1, wherein said sheet materials constituting said core layer comprise a no-chlorine-containing material.

10. - 16. (Cancelled)

17. (Currently Amended) An IC card comprising:

an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, a sealing material which encapsulates said IC chip, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate and formed on said IC chip through said sealing material; and

a core layer comprising a plurality of sheet materials having said IC module disposed therebetween,

wherein,

in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole (a) for containing therein said IC chip said sealing material and said chip reinforcing plate, and (b) formed to penetrate the adjacent sheet materials in a region corresponding to an IC mounted portion of said IC module before placing said IC chip therein,

a relationship of $(B1 + C1) - 20\ \mu m \leq A \leq (B1 + C1) + 10\ \mu m$ is satisfied, wherein A (μm) represents the sum of heights of said through holes, B1 (μm) represents a projection height on an IC mounted surface of said IC module, and C1 (μm) represents a projection height on an IC non-mounted surface of said IC module,

the relationships $B = B1 \pm 30\ \mu m$, and $C = C1 \pm 30\ \mu m$ are satisfied, wherein B (μm) represents a height of said through hole on the side of the IC mounted surface of said IC module, and C (μm) represents a height of said through hole on the side of the IC non-mounted surface of said IC module, and

said through holes are larger than at least one of a length and a width of said chip reinforcing plate so as to form at least one empty region in said through holes.

18. - 20. (Cancelled)